

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

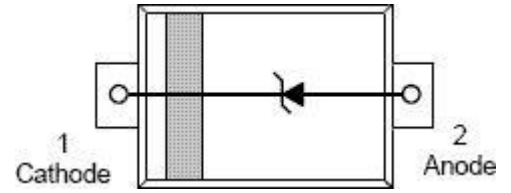
Product data sheet

Applications

- Cellular phones
- Portable devices
- Digital cameras
- Power supplies

Features

- Small Body Outline Dimensions
- Low Body Height
- Peak Power up to 200 Watts @ 8 x 20 μ sPulse
- Low Leakage
- Response Time is Typically < 1 ns
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- IEC61000-4-2 Level 4 ESD Protection
- IEC61000-4-4 Level 4 EFT Protection
- We declare that the material of product compliance with RoHS requirements.



SOD-523

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified. VF = 0.9V at IF = 10mA

Device	V _{RWM} (V)	I _R (μ A) @ V _{RWM}	V _{BR} (V)@ I _T (Note 1)	I _T	V _c (V) @ I _{PP} =5 A*	V _c (V) @ Max I _{PP} *	I _{PP} (A)*	P _{PK} (W)*	C (pF)
	Max	Max	Min	mA	Typ	Max	Max	Max	Typ
ESD3V3D5-MS	3.3	1.0	5.0	1.0	8.4	14.1	11.2	158	105
ESD5V0D5-MS	5.0	1.0	6.2	1.0	11.6	18.6	9.4	174	80
ESD7V0D5-MS	7.0	1.0	7.5	1.0	13.5	22.7	8.8	200	65
ESD12VD5-MS	12	1.0	13.5	1.0	25.5	30	5	150	55

Absolute Ratings (T_{amb}=25°C)

Symbol	Parameter	Value	Units	
P _{PP}	Peak Pulse Power (t _p = 8/20 μ s)	200	W	
T _L	Maximum lead temperature for soldering during 10s	260	°C	
T _{stg}	Storage Temperature Range	-55 to +150	°C	
T _{op}	Operating Temperature Range	-40 to +125	°C	
T _j	Maximum junction temperature	150	°C	
	IEC61000-4-2 (ESD)	air discharge contact discharge	\pm 15 \pm 8	KV
	IEC61000-4-4 (EFT)		40	A
	ESD Voltage	Per Human Body Model	16	KV

Electrical Parameter

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
I_T	Test Current
V_{BR}	Breakdown Voltage @ I_T

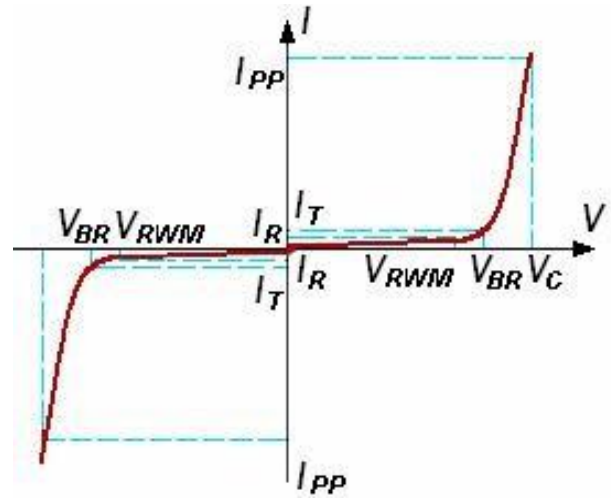


FIG1: Pulse Waveform

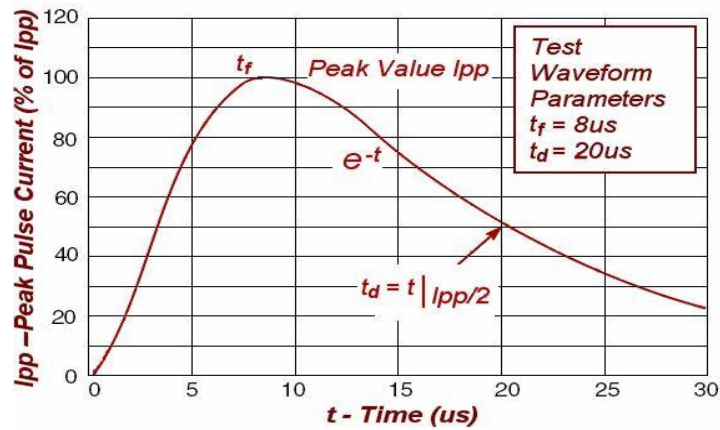
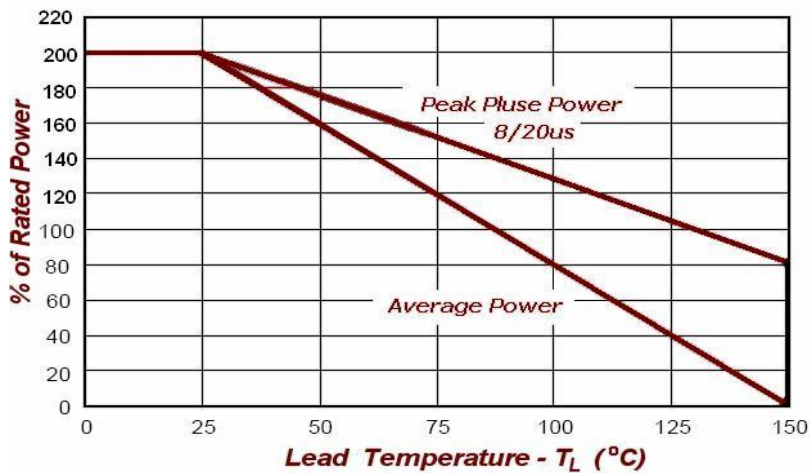
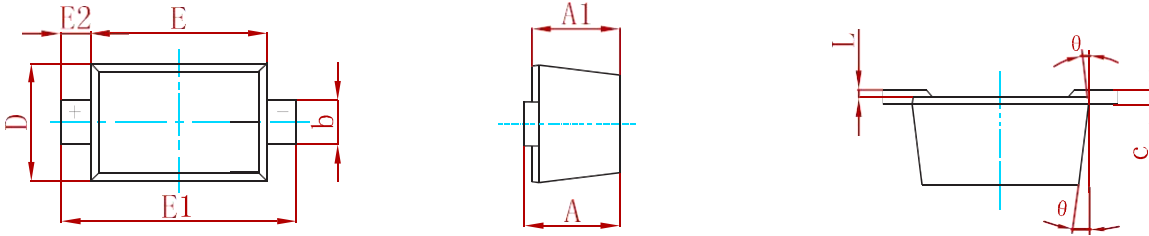


FIG2: Power Derating

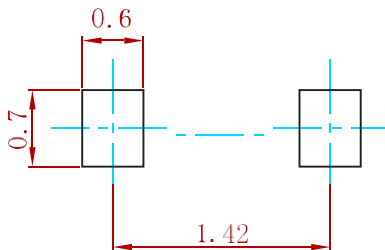


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.510	0.770	0.020	0.031
A1	0.500	0.700	0.020	0.028
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	0.750	0.850	0.030	0.033
E	1.100	1.300	0.043	0.051
E1	1.500	1.700	0.059	0.067
E2	0.200 REF		0.008 REF	
L	0.010	0.070	0.001	0.003
θ	7° REF		7° REF	

Suggested Pad Layout



- Note:
1. Controlling dimension: in millimeters.
 2. General tolerance: $\pm 0.05\text{mm}$.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
ESDXXXD5-MS	SOD-523	3000

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